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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

**Katsuhito Kikuma et al.**

Confirmation Number: **6338**

Serial No.: **10/623,490**

Group Art Unit: **2818**

Filed: **July 22, 2003**

Examiner: **Mai-Huong Tran**

For: **STACKED SEMICONDUCTOR DEVICE ...**

Attorney Docket: **010944A**

**AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Date: **April 21, 2003**

Sir:

This paper is in response to the Office Action mailed on February 18, 2004. No extension fee is due. However, any fees needed for this paper may be charged to Deposit Account No. 01-2340 and, in the event this paper is not timely filed, then consider this paper as a petition for an appropriate extension of time.

The new claims are patentable for the reasons below.

New claim 11 (corresponding to old claim 1) recites a "circuit board" where claim 1 recites a "substrate." The term "circuit board" is found in the specification at page 12, second and third paragraphs. Claim 11 also introduces "upper" and "lower," to make the claim easier to understand but without loss of generality. (An explanatory paragraph is added to the specification.) The "external device" is recited in the claim 11 preamble, and the first and second terminals are referred to as "first wire bonding terminals" and "second wire bonding terminals." Claim 11 is a Jepson claim.